

## C1206X331GDGACTU

Aliases (C1206X331GDGAC7800)

SMD Comm COG HV Flex, Ceramic, 330 pF, 2%, 1,000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1206, 1.5 mm



Click [here](#) for the 3D model.

### General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

### Dimensions

Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	1.2mm +/-0.15mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

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